

FILM THICKNESS MEASUREMENT APPARATUS, POLISHING APPARATUS, AND
FILM THICKNESS MEASUREMENT METHOD

ABSTRACT

Provided is a technique capable of suppressing a shortage of a light amount of a reflected light from wiring patterns even when a film thickness of a film is thick. A film thickness measurement apparatus 30 is applicable to a polishing apparatus 10 for polishing a film 202 of a substrate 200. The film 202 includes a plurality of wiring patterns. The film thickness measurement apparatus 30 includes a light emitter 43 configured to project an emitted light L1 during polishing of the film by the polishing apparatus, an optical condenser 44 configured to condense the emitted light projected from the light emitter to provide a predetermined spot size D and project the light onto the film, and a light receiver 45 configured to receive a reflected light L2 reflected from the film. The predetermined spot size is smaller than a minimum width of respective wiring patterns constituting the plurality of wiring patterns.

Selected Drawing: Fig. 6